MATERIAL DECLARATION SHEET

Material Number	PTVS3-076C-TH		
Product Line	Semiconductor Products		
Compliance Date	December 12th 2013		
RoHS Compliant	Yes	MSL	Not Applicable

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.231000	Bisphenol Epoxy Resin	1675-54-3	40.00	5.42	13.55
				Epoxy Resin	25085-99-8	20.00	2.71	
				Crystalline Silica	14464-46-1	23.00	3.12	
				Brominated Epoxy Resin	40039-93-8	12.00	1.63	
				Iron Oxide	51274-00-1	2.00	0.27	
				Titanium Oxide	13463-67-7	3.00	0.41	
2	Electrodes	Copper	0.784987	Copper	7440-50-8	99.10	45.64	46.06
				Silver	7440-22-4	0.40	0.18	
				Other	-	0.50	0.23	
3	Terminations	Copper	0.489386	Copper	7440-50-8	99.50	28.57	28.71
				Other	-	0.50	0.14	
4	Termination Finish	Silver	0.002614	Silver	7440-22-4	100.00	0.15	0.15
5	Chip	Silicon Die	0.070045	Silicon	7440-21-3	85.91	3.53	4.11
				Aluminium	7429-90-5	4.93	0.20	
				Nickel	7440-02-0	8.73	0.36	
				Gold	7440-57-5	0.42	0.02	
6	Die Attach	Solder	0.057154	Lead	7439-92-1	92.50	3.10	3.35
				Tin	7440-31-5	5.00	0.17	
				Silver	7440-22-4	2.50	0.08	
7	Die Coating	Silicone	0.069229	Polysiloxane	63148-62-9	22.11	0.90	4.06
				Chromium Sesquioxide	1308-38-9	5.67	0.23	
				Fumed Silica	112945-52-5	11.11	0.45	
				Filler	Trade Secret	61.11	2.48	
		Total Weight	1.704415					

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